

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

18.03.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	168		2		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3		
		70	L2			
C-STD-FR4-ML-0.203mm-070+070-TG150-H...	50203119	203		4	A00	B00
		70	L3			
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	168		5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	7		

Thickness after Pressing

B00:

690 µm

Tol+:

80 µm

Tol-:

80 µm

Dmax:

770 µm

Dmin:

610 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

800 µm

Tol+:

80 µm

Tol-:

80 µm

Dmax:

880 µm

Dmin:

720 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

715 µm

Version 1.2.20.35

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